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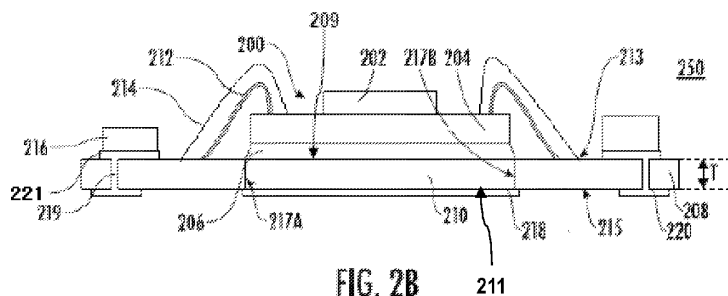
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(54) Title: METHODS OF MANUFACTURING LIGHT-EMITTING DEVICES WITH METAL INLAYS AND BOTTOM CONTACTS



(57) Abstract: Methods of manufacturing light-emitting devices are described herein. A method includes obtaining a packaging substrate. The packaging substrate includes an embedded metal inlay, vias in the packaging substrate and contacts on a bottom surface of the packaging substrate, each electrically coupled to a respective one of the vias. The method also includes forming a hybridized device, attaching a bottom surface of the hybridized device to a top surface of the metal inlay, and wirebonding a top surface of the hybridized device to a top surface of the packaging substrate using a plurality of conductive connectors.

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